

Single P-channel MOSFET

ELM4P2607FAA-S

<http://www.elm-tech.com>

■General description

ELM4P2607FAA-S uses advanced trench technology to provide excellent $R_{ds(on)}$, low gate charge and low gate threshold voltage.

■Features

- $V_{ds} = -20V$
- $I_d = -6.9A$ ($V_{gs} = -4.5V$)
- $R_{ds(on)} = 30m\Omega$ ($V_{gs} = -4.5V$)
- $R_{ds(on)} = 38m\Omega$ ($V_{gs} = -2.5V$)
- $R_{ds(on)} = 55m\Omega$ ($V_{gs} = -1.8V$)

■Maximum absolute ratings

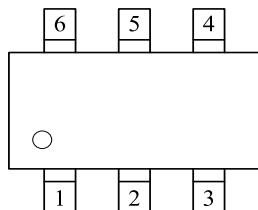
Parameter	Symbol	Limit	Unit	Note
Drain-source voltage	V_{ds}	-20	V	
Gate-source voltage	V_{gs}	± 12	V	
Continuous drain current ($V_{gs} = -4.5V$)	I_d	-6.9	A	1
Ta=70°C		-5.4		
Pulsed drain current	I_{dm}	-20	A	2
Power dissipation	P_d	1.0	W	3
Junction and storage temperature range	T_j, T_{stg}	-55 to +150	°C	

■Thermal characteristics

Parameter	Symbol	Typ.	Max.	Unit	Note
Thermal resistance junction-to-ambient	$R_{\theta ja}$	-	50	°C/W	1
Thermal resistance junction-to-ambient		-	100		

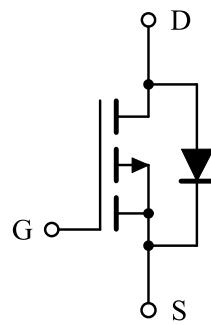
■Pin configuration

TSOP-6(TOP VIEW)



Pin No.	Pin name
1	DRAIN
2	DRAIN
3	GATE
4	SOURCE
5	DRAIN
6	DRAIN

■Circuit



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■Electrical characteristics

T_j=25°C. Unless otherwise noted.

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
STATIC PARAMETERS							
Drain-source breakdown voltage	BVdss	V _{gs} =0V, I _d =-250μA	-20	-	-	V	
Zero gate voltage drain current	Idss	V _{ds} =-16V, V _{gs} =0V	-	-	-1	μA	
		V _{ds} =-16V, V _{gs} =0V, T _j =55°C	-	-	-5		
Gate-body leakage current	I _{gss}	V _{ds} =0V, V _{gs} =±12V	-	-	±100	nA	
Gate threshold voltage	V _{gs(th)}	V _{ds} =V _{gs} , I _d =-250μA	-0.3	-0.5	-1.0	V	
Static drain-source on-resistance	R _{ds(on)}	V _{gs} =-4.5V, I _d =-4.0A	-	25	30	mΩ	2
		V _{gs} =-2.5V, I _d =-2.0A	-	32	38		
		V _{gs} =-1.8V, I _d =-1.5A	-	42	55		
Forward transconductance	G _f s	V _{ds} =-5V, I _d =-4A	-	21	-	S	
Diode forward voltage	V _{sd}	I _s =-1A, V _{gs} =0V	-	-	-1	V	2
Max. body-diode continuous current	I _s	V _{gs} =V _{ds} =0V, Force Current	-	-	-6.9	A	1, 4
Pulsed source current	I _{sm}		-	-	-18.8	A	2, 4
DYNAMIC PARAMETERS							
Input capacitance	C _{iss}	V _{gs} =0V, V _{ds} =-15V, f=1MHz	-	2280	-	pF	
Output capacitance	C _{oss}		-	220	-	pF	
Reverse transfer capacitance	C _{rss}		-	187	-	pF	
SWITCHING PARAMETERS							
Total gate charge (-4.5V)	Q _g	V _{gs} =-4.5V, V _{ds} =-15V I _d =-4A	-	27.3	-	nC	
Gate-source charge	Q _{gs}		-	3.6	-	nC	
Gate-drain charge	Q _{gd}		-	6.5	-	nC	
Turn-on delay time	t _{d(on)}	V _{gs} =-4.5V, V _{ds} =-10V I _d =-4A, R _{gen} =3.3Ω	-	9.2	-	ns	
Turn-on rise time	t _r		-	59.0	-	ns	
Turn-off delay time	t _{d(off)}		-	99.0	-	ns	
Turn-off fall time	t _f		-	71.0	-	ns	
Reverse recovery time	t _{rr}	I _f =-4A, dI/dt=100A/μs	-	52	-	nS	
Reverse recovery charge	Q _{rr}		-	28	-	nC	

NOTE :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300μs and duty cycle ≤ 2%.
3. The power dissipation is limited by 150°C junction temperature.
4. The data is theoretically the same as I_d and I_{dm}, in real applications, should be limited by total power dissipation.

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■Typical electrical and thermal characteristics

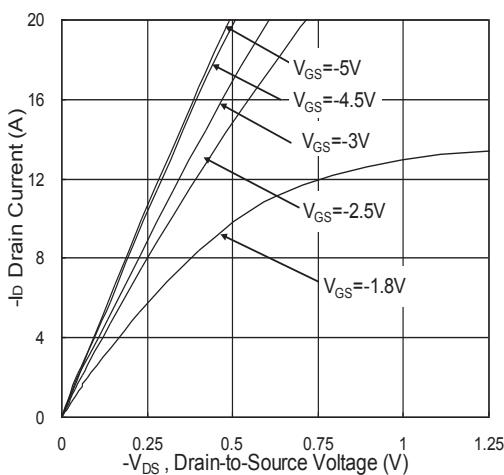


Fig.1 Typical Output Characteristics

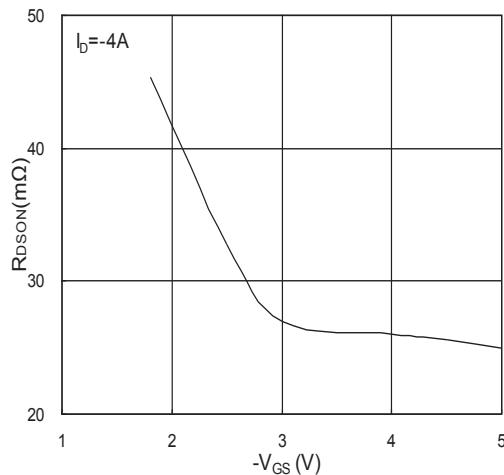


Fig.2 On-Resistance vs. Gate-Source

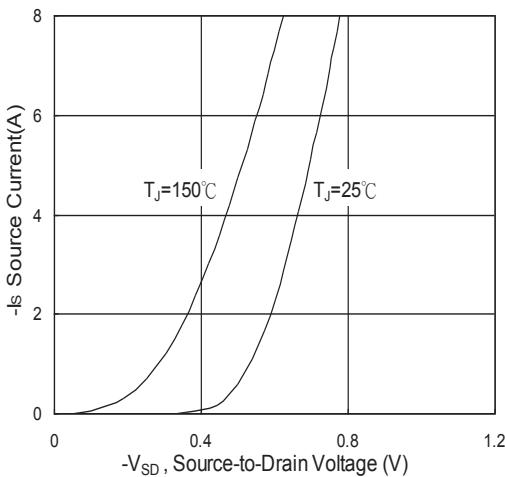


Fig.3 Forward Characteristics Of Reverse

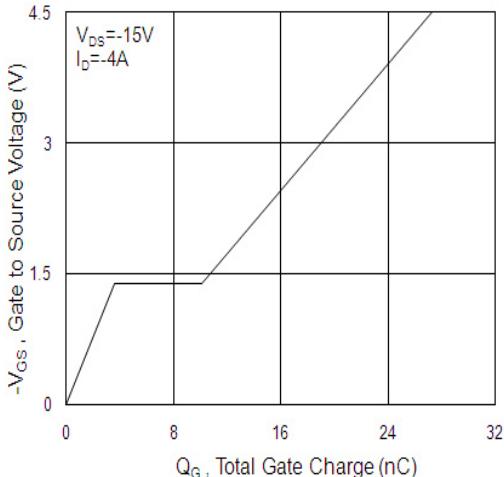


Fig.4 Gate-Charge Characteristics

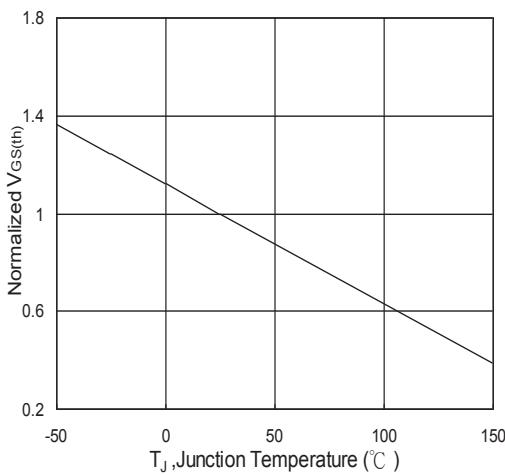


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

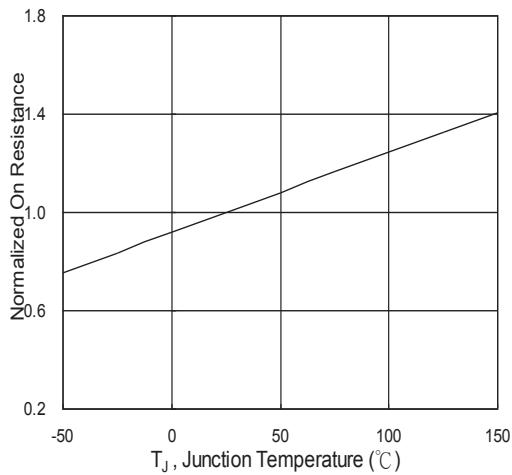


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

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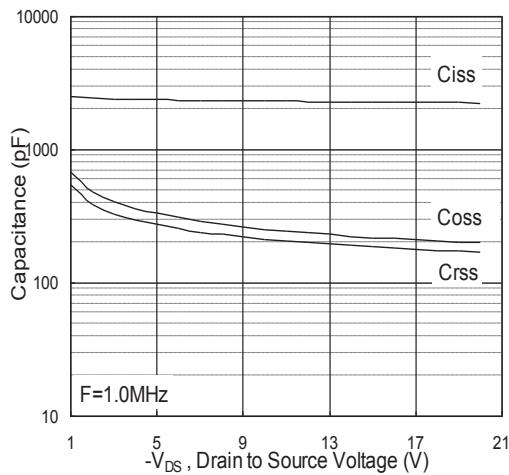


Fig.7 Capacitance

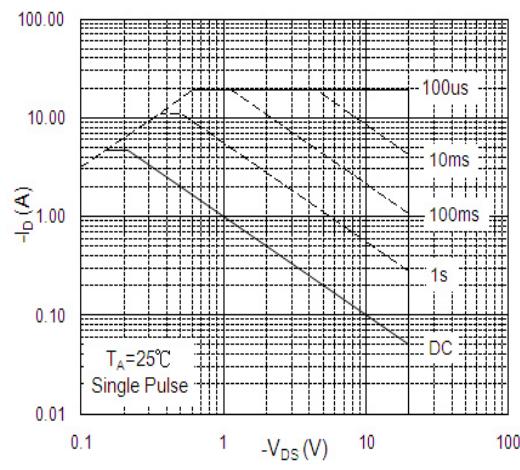


Fig.8 Safe Operating Area

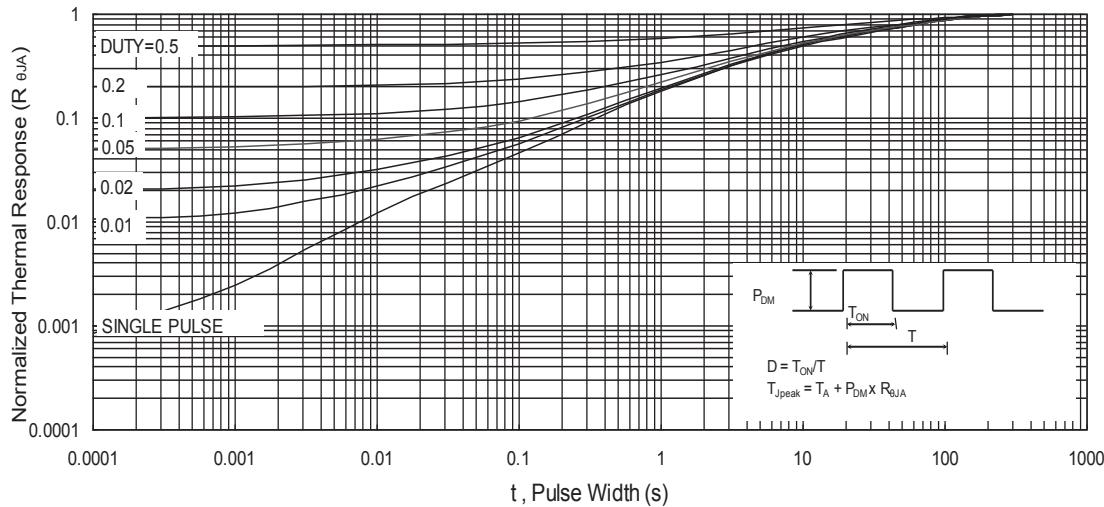


Fig.9 Normalized Maximum Transient Thermal Impedance

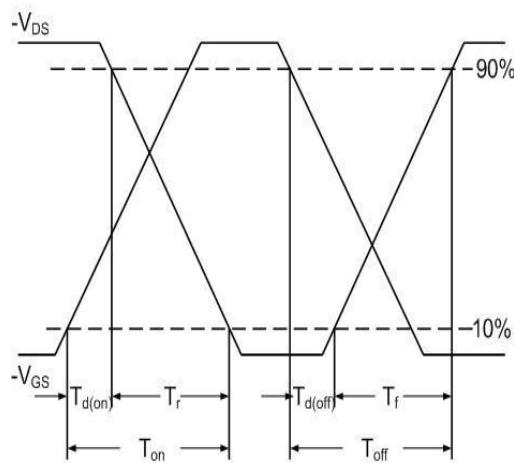


Fig.10 Switching Time Waveform

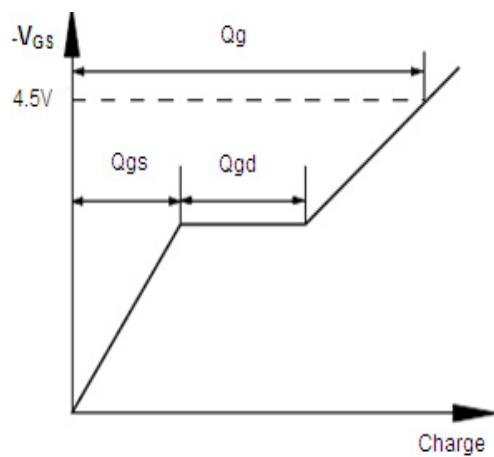


Fig.11 Gate Charge Waveform